

Ultra Small Temperature Switches with Pin Selectable Hysteresis

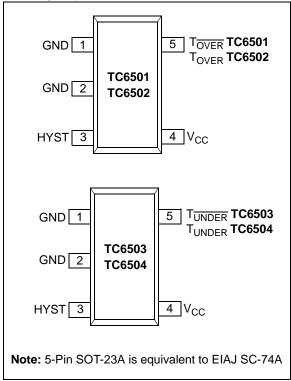
Features

- 5-Pin SOT-23A
- Factory-programmed Thresholds from -45°C to +125°C in 10°C Increments
- Pin Selectable +2°C or +10°C Hysteresis
- ±0.5°C (Typ) Threshold Accuracy Over Full Temperature Range
- No External Components Required
- 17 µA Supply Current (Typ)

Applications

- Thermal Management in PCs and Servers
- Over-temperature Fail-safe Circuits
- Simple Fan Controller
- Temperature Alarms
- Projectors/Printers
- Notebook Computers
- Network Boxes

Package Types



General Description

The TC6501/2/3/4 are SOT-23 temperature switches that require no external components and are available with factory-programmed temperature thresholds. A choice of factory-trimmed temperature trip points are also available. Pin-selectable hysteresis of +2°C or +10°C allows flexibility to the design of the application. These parts typically consume only 17 μ A of current and operate over the entire -55°C to +135°C temperature range, while offering accuracies of ±0.5°C (typ).

The TC6501 and TC6503 have an open-drain, activelow output, which targets microcontroller reset control. The TC6502 and TC6504 have a CMOS, active-high output designed to drive the logic level MOSFET that turns on a fan or heater element.

The TC6501/TC6502 are designed for hot temperature monitoring (+35°C to +125°C). These devices assert a logic signal when the temperature goes above the threshold. The TC6503/TC6504 are optimized for cold temperature monitoring (-45°C to +15°C) and assert a logic signal when the temperature goes below the threshold.

The TC6501/2/3/4 are offered with five standard temperature thresholds. Available in 5-Pin SOT-23A packages, these parts are ideal for applications requiring high integration, small size, low power and low installed cost.

+2.7V to +5.5V 100 pF \pm V_{CC} V_{CC} V_{CC} PIC[®] Microcontroller INT GND GND HYST GND

Functional Block Diagram

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings*

Supply Voltage (V _{CC})0.3V to +7V
Input Current (All Pins)20 mA
Output Current (All Pins)20 mA
Operating Temperature Range 55°C to +135°C
Storage Temperature Range 65°C to +165°C
T _{OVER} (TC6501)0.3V to +7V
T _{OVER} (TC6502)0.3V to (V _{CC} + 0.3V)
T _{UNDER} (TC6503)0.3V to 7V
T _{UNDER} (TC6504)0.3V to (V _{CC} + 0.3V)
All Other Pins0.3V to (V _{CC} + 0.3V)
Maximum Junction Temperature, T _J 150°C
Power Dissipation (T _A = +70°C): (Derate 7.1 mW/°C Above +70°C)570 mW

* **Notice:** Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL SPECIFICATIONS

Electrical Characteristics: Unless otherwise noted, $V_{CC} = +2.7V$ to +5.5V, $R_{PULL-UP} = 100 \text{ k}\Omega$ (**TC6501/TC6503** only), 100 pF decoupling capacitor from V_{CC} to GND, $T_{AMB} = -55^{\circ}C$ to +135°C. Typical values are at $T_A = +25^{\circ}C$.

Parameter	Symbol	Min	Тур	Max	Unit	Test Conditions
Supply Voltage Range	V _{CC}	2.7	-	5.5	V	
Supply Current	I _{CC}	_	17	40	μA	
HYST Input Threshold	VIH	0.8 x V _{CC}	_	_	V	
HYST Input Threshold	V _{IL}	_	_	0.2 x V _{CC}	V	
Temperature Threshold Accuracy (Note 1)	ΔT_{TH}	-6	±0.5	6	°C	-45°C to -25°C
		-4	±0.5	4	°C	-15°C to +15°C
		-4	±0.5	4	°C	+35°C to +65°C
		-6	±0.5	6	°C	+75°C to +125°C
Temperature Threshold Hysteresis	T _{HYST}	_	2.0	_	°C	HYST = GND
		_	10	_	°C	HYST = V _{CC}
Output Voltage High	V _{OH}	0.8 x V _{CC}	_	—	V	I _{SOURCE} = 500 μA, V _{CC} > 2.7V (TC6502/TC6504 Only)
		V _{CC} - 1.5	_	—	V	I _{SOURCE} = 800 μA, V _{CC} > 4.5V (TC6502/TC6504 Only)
Output Voltage Low	V _{OL}	—	_	0.3	V	I_{SINK} = 1.2 mA, V_{CC} > 2.7V
		—	_	0.4	V	$I_{SINK} = 3.2 \text{ mA}, V_{CC} > 4.5 \text{V}$
Open-Drain Output Leakage Current		_	10	_	nA	V _{CC} = 2.7V, T _{UNDER} = 5.5V (TC6503); T _{OVER} = 5.5V (TC6501)

Note 1: The TC6501/2/3/4 are available with internal, factory-programmed temperature trip thresholds from -45°C to +125°C, in +10°C increments.

2.0 TYPICAL PERFORMANCE CURVES

- **Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.
- **Note:** Unless otherwise noted, $V_{CC} = 5.0V$, $R_{PULL-UP} = 100 \text{ k}\Omega$ (**TC6501/TC6503** only), 100 pF decoupling capacitor from V_{CC} to GND, $T_{AMB} = +25^{\circ}C$.

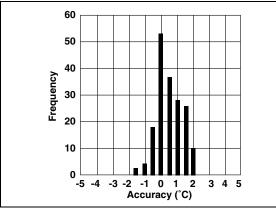


FIGURE 2-1:

Trip Threshold Accuracy.

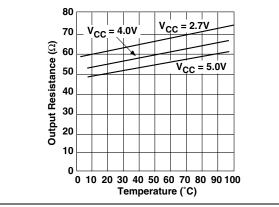


FIGURE 2-2: Temperature.

Output Sink Resistance vs.

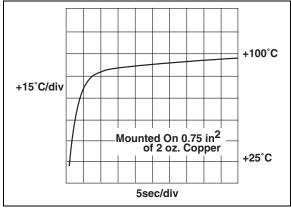


FIGURE 2-3: Thermal Step Response in Perfluorinated Fluid (SOT-23).

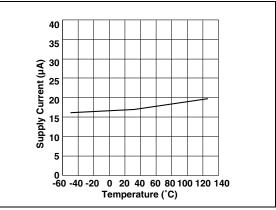


FIGURE 2-4: Temperature.

Supply Current vs.

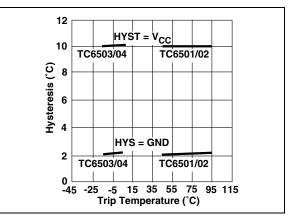


FIGURE 2-5: Hysteresis vs. Trip Temperature.

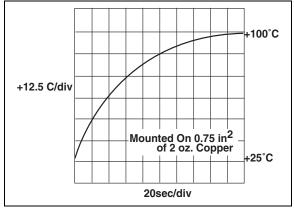


FIGURE 2-6: Thermal Step Response in Still Air (SOT-23).

Note: Unless otherwise noted, V_{CC} = 5.0V, $R_{PULL-UP}$ = 100 k Ω (TC6501/TC6503 only), 100 pF decoupling capacitor from V_{CC} to GND, T_{AMB} = +25°C.

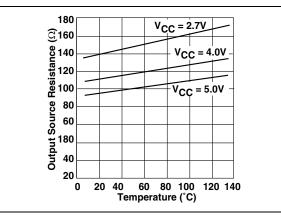


FIGURE 2-7: Output Source Resistance vs. Temperature (TC6502).

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TC6501	TC6502	TC6503	TC6504	Symbol	Description
1, 2	1, 2	1, 2	1, 2	GND	Ground
3	3	3	3	HYST	Hysteresis Input
4	4	4	4	V _{CC}	Supply Input (+2.7V to +5.5V)
5	—	-	—	TOVER	Open-Drain, Active-Low Output
—	5		—	T _{OVER}	Push/Pull Active-High Output
—	_	5	—	T _{UNDER}	Open-Drain, Active-Low Output
_	_		5	T _{UNDER}	Push/Pull Active-High Output

TABLE 3-1: PIN FUNCTION TABLE

3.1 Ground

Connect the device ground pins directly to the PCB ground and minimize the length of the connection. The thermal resistance to the die is at a minimum at Pin 2.

3.2 Hysteresis Input (HYST)

Either 2°C (GND) or 10°C (V_{CC}) of hysteresis is selected by connecting HYST to GND or V_{CC}.

3.3 Supply Input (V_{CC})

A 100 pF or greater decoupling capacitor from V_{CC} to GND is recommended.

3.4 Open-Drain, Active-Low Output (TC6501) (T_{OVER})

The voltage at the $T_{\overline{OVER}}$ pin is equal to a logic-low level if the sensor detects a temperature that is greater than the factory-programmed threshold temperature. Because this is an open-drain output, an external pull-up resistor is required (a 100 k Ω pull-up resistor is recommended). The voltage on this pin can be higher than V_{CC}, though the voltage must not exceed the absolute maximum input voltage of 7.0V.

3.5 Push/Pull Active-High Output (TC6502) (T_{OVER})

The voltage at $T_{\rm OVER}$ is equal to a logic-high level if the sensor detects a temperature greater than the factory-programmed threshold temperature.

3.6 Open-Drain, Active-Low Output (TC6503) (T_{UNDER})

The voltage at the T_{UNDER} pin is equal to a logic-low level if the sensor detects a temperature that is less than the factory-programmed threshold temperature. Because this is an open-drain output, an external pull-up resistor is required (a 100 k Ω pull-up resistor is recommended). The voltage on this pin can be higher than V_{CC}, though the voltage must not exceed the absolute maximum input voltage of 7.0V

3.7 Push/Pull Active-High Output (TC6504) (T_{UNDER})

The voltage at T_{UNDER} is equal to a logic-high level if the sensor detects a temperature less than the factory-programmed threshold temperature.

4.0 DETAILED DESCRIPTION

The TC6501/2/3/4 integrate a temperature sensor with a factory-programmed threshold switch (see Functional Block Diagrams in Figure 5-4 through Figure 5-7). A logic signal is asserted when the die temperature crosses the factory-programmed threshold. An external hysteresis input pin allows the user to select either 2°C or 10°C hysteresis to give further flexibility to the design of the application. The TC6501 and TC6502 are intended for a temperature range of 35°C to 125°C in 10°C increments. The TC6501 has an open-drain output, while the TC6502 has a push-pull output stage.

The TC6503 and TC6504 are intended for a cold temperature range of -45° C to $+15^{\circ}$ C in 10°C increments. The TC6503 has an open-drain output, while the TC6504 has a push/pull output stage. The TC6501 and TC6503 are intended for applications with a microcontroller reset input. The TC6502 and TC6504 are intended for applications where a fan or heater element is turned on.

Please contact Microchip Technology for the availability of a particular temperature threshold not included in Table 4-1.

4.1 Hysteresis Input

To prevent the output from "chattering" at or near the trip point temperature, a selectable HYST input pin is provided. Hysteresis can be externally selected at 2°C (HYST = GND) or 10°C (HYST = V_{CC}) by means of the CMOS compatible HYST input pin. Do not let the HYST pin float, as this could cause an increase in supply current. The hysteresis does not depend on the part's programmed trip threshold.

TABLE 4-1:FACTORY-PROGRAMMEDTHRESHOLD RANGE

Part Number	Threshold (T _{TH}) Range
TC6501	+35°C < T _{TH} < +125°C
TC6502	+35°C < T _{TH} < +125°C
TC6503	-45°C < T _{TH} < +15°C
TC6504	-45°C < T _{TH} < +15°C

4.2 Thermal Considerations

With a 17 μ A typical supply current, the TC6501/2/3/4 dissipates very little power. Thus, the die temperature is basically the same as the package temperature. To minimize the error in temperature readings, the load current should be limited to a few milliamps. For example, the typical thermal resistance of a 5-Pin SOT-23A package is 140°C/W. If, for instance, the TC6501 had to sink 1 mA, and the output voltage is ensured to be less than 0.3V, an additional 0.3 mW of power is dissipated within the temperature sensor. This corresponds to a 0.042°C rise in die temperature.

Temperature-monitoring accuracy depends on the thermal resistance between the device being monitored and the temperature switch die. Heat flows primarily through the leads onto the die. Pin 2 provides the lowest thermal resistance to the die. To achieve the best temperature-monitoring results, the TC6501/2/3/4 should be placed closest to the device being monitored. Additionally, a short and wide copper trace from pin 2 to the device should be used. In some cases, the 5-Pin SOT-23A package can be placed directly under the socketed microcontroller for improved thermal contact.

5.0 APPLICATIONS

The TC6501 and TC6503 have open-drain outputs and are, therefore, intended to interface as microcontroller reset inputs. Moreover, the combination of these two devices can be used to implement a temperature window alarm by wire-ORing the outputs and using an external pull-up resistor (see Figure 5-1).

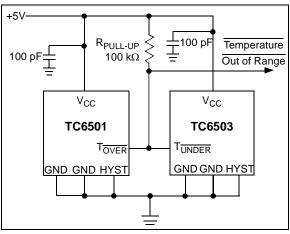


FIGURE 5-1: Over and Under Temperature Alarm.

The TC6502 can be used to control a DC fan. The fan turns on when the sensed temperature rises above the factory-set threshold and remains on until the temperature falls below threshold minus the hysteresis selected. An additional fail-safe measure could be designed by using a second TC6502 with a higher temperature threshold to alert the user of an impending thermal shutdown, should the temperature continue to rise (see Figure 5-2).

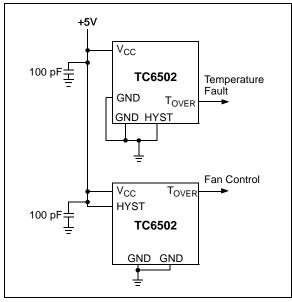


FIGURE 5-2: Fan Control with Over Temperature Alert.

The TC6504, with its push-pull output, may be used in a similar fashion to turn on a heater element at cold temperatures (see Figure 5-3).

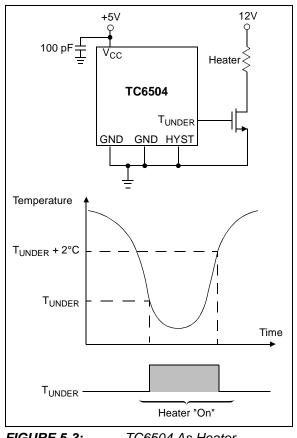
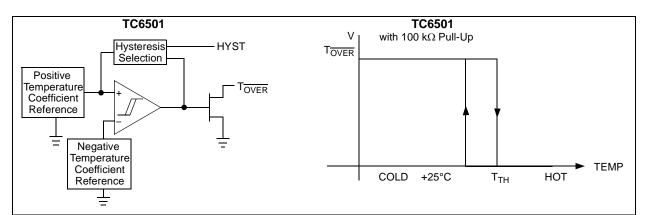


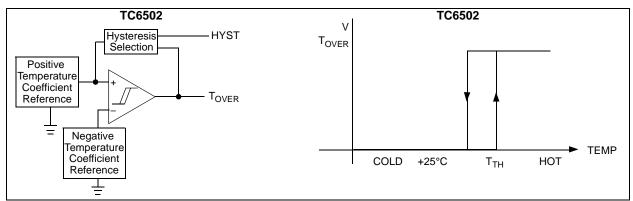
FIGURE 5-3: Thermostat.

TC6504 As Heater



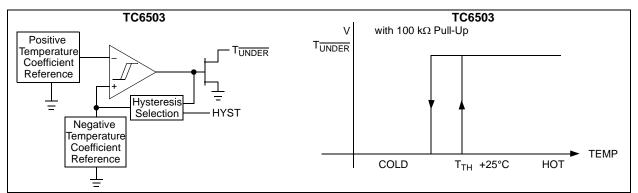


TC6501 Functional Block Diagram.



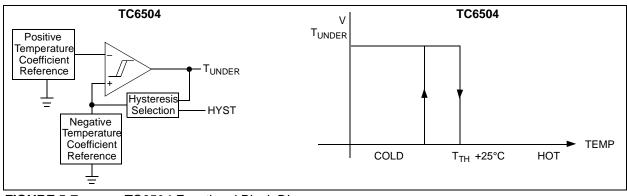


TC6502 Functional Block Diagram.





TC6503 Functional Block Diagram.

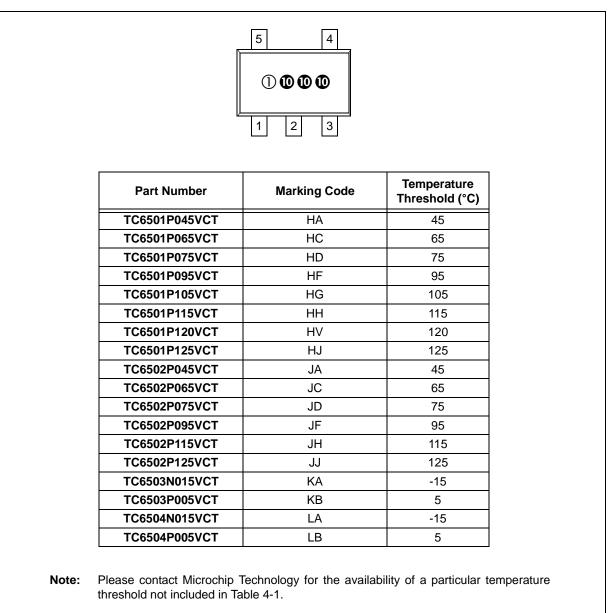




TC6504 Functional Block Diagram.

6.0 PACKAGING INFORMATION

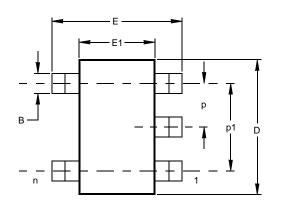
6.1 Package Marking Diagram

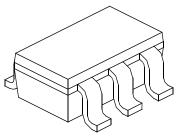


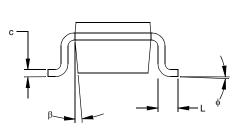
Legend	: XXX Y YY WW NNN (e3) *	Customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
	be carrie	nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available s for customer-specific information.

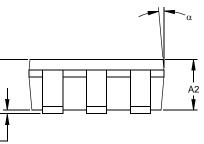
5-Lead Plastic Small Outline Transistor (CT) (SOT-23)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging









	Units			INCHES*			MILLIMETERS		
Dimensio	on Limits	MIN	NOM	MAX	MIN	NOM	MAX		
Number of Pins	n		5			5			
Pitch	р		.038			0.95			
Outside lead pitch (basic)	p1		.075			1.90			
Overall Height	А	.035	.046	.057	0.90	1.18	1.45		
Molded Package Thickness	A2	.035	.043	.051	0.90	1.10	1.30		
Standoff §	A1	.000	.003	.006	0.00	0.08	0.15		
Overall Width	Е	.102	.110	.118	2.60	2.80	3.00		
Molded Package Width	E1	.059	.064	.069	1.50	1.63	1.75		
Overall Length	D	.110	.116	.122	2.80	2.95	3.10		
Foot Length	L	.014	.018	.022	0.35	0.45	0.55		
Foot Angle	ф	0	5	10	0	5	10		
Lead Thickness	С	.004	.006	.008	0.09	0.15	0.20		
Lead Width	В	.014	.017	.020	0.35	0.43	0.50		
Mold Draft Angle Top	α	0	5	10	0	5	10		
Mold Draft Angle Bottom	β	0	5	10	0	5	10		

А

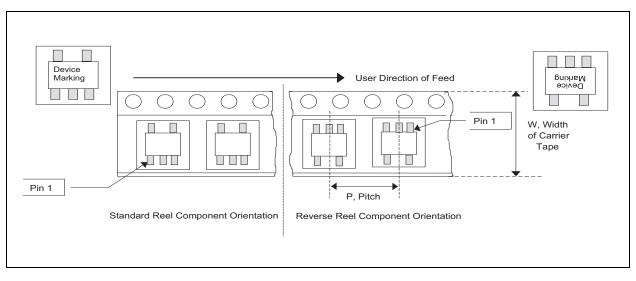
A1

* Controlling Parameter § Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MO-178 Drawing No. C04-091





7.0 REVISION HISTORY

Revision E (December 2012)

Added a note to the package outline drawing.

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO. XXX	<u>x xxxxx</u>	Examples:
Device Stand	ard Package	a) TC6501P045VCTTR: 5-Pin SOT-23A, 45°C, Open-Drain, tape and re
Temperature Threshold		b) TC6501P065VCTTR: 5-Pin SOT-23A, 65°C, Open-Drain, tape and re
		c) TC6501P095VCTTR: 5-Pin SOT-23A, 95°C, Open-Drain, tape and re
Device:	TC6501: Ultra Small Temp Switch with Pin-Selectable Hysteresis TC6502: Ultra Small Temp Switch with Pin-Selectable	d) TC6501P095VCTRT: 5-Pin SOT-23A, 95°C, Open-Drain, reverse tape and reel.
	Hysteresis TC6503: Ultra Small Temp Switch with Pin-Selectable Hysteresis TC6504: Ultra Small Temp Switch with Pin-Selectable	e) TC6501P125VCTRT: 5-Pin SOT-23A, 125°C, Open-Drain, reverse tape and reel.
	Hysteresis	a) TC6502P045VCTTR 5-Pin SOT-23A, 45°C, Push-Pull, tape and ree
Standard Temperature Threshold:	N015 = -15°C (TC6503, TC6504) P005 = 5°C (TC6503, TC6504	b) TC6502P065VCTTR 5-Pin SOT-23A, 65°C, Push-Pull, tape and ree
P065 = P075 = P095 = P105 =	$P065 = 65^{\circ}C (TC6501, TC6502)$	c) TC6502P095VCTTR: 5-Pin SOT-23A, 95°C, Push-Pull, tape and ree
	$P105 = 105^{\circ}C (TC6501)$	a) TC6503N015VCTTR 5-Pin SOT-23A, -15°C, Open-Drain, tape and re
	$\begin{array}{rcl} P115 & = & 115^{\circ}C \ (TC6501, TC6502) \\ P120 & = & 120^{\circ}C \ (TC6501) \\ P125 & = & 125^{\circ}C \ (TC6501, TC6502) \end{array}$	b) TC6503P005VCTTR: 5-Pin SOT-23A, 5°C, Open-Drain, tape and re
Package:	VCTTR = SOT-23, 5-lead (Tape and Reel)	a) TC6504N015VCTTR: 5-Pin SOT-23A, -15°C, Push-Pull, tape and ree
	VCTRT = SOT-23, 5-lead (Reverse Tape and Reel) (Available only in 95°C and 125°C temperatures for TC6501)	b) TC6504P005VCTTR: 5-Pin SOT-23A, 5°C, Push-Pull, tape and ree

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

- Your local Microchip sales office 1.
- The Microchip Worldwide Site (www.microchip.com) 2.

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

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